



TinyLogic UHS Dual 2-Input OR Gate

NC7WZ32

Description

The NC7WZ32 is a dual 2-Input OR Gate from **onsemi**'s Ultra High Speed Series of TinyLogic. The device is fabricated with advanced CMOS technology to achieve ultra high speed with high output drive while maintaining low static power dissipation over a very broad V_{CC} operating range. The device is specified to operate over the 1.65 V to 5.5 V V_{CC} range. The inputs and output are high impedance when V_{CC} is 0 V. Inputs tolerate voltages up to 6.5 V independent of V_{CC} operating voltage.

Features

- Space Saving US8 Surface Mount Package
- MicroPak[™] Pb–Free Leadless Package
- Ultra High Speed: t_{PD} = 2.4 ns Typ. into 50 pF at 5 V V_{CC}
- High Output Drive: ±24 mA at 3 V V_{CC}
- Broad V_{CC} Operating Range: 1.65 V to 5.5 V
- Matches the Performance of LCX when Operated at 3.3 V V_{CC}
- Power Down High Impedance Inputs / Output
- Overvoltage Tolerant Inputs Facilitate 5 V to 3 V Translation
- Proprietary Noise / EMI Reduction Circuitry Implemented
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

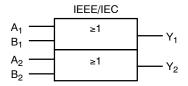


Figure 1. Logic Symbol

1

MARKING DIAGRAMS



UQFN8 1.6X1.6, 0.5P CASE 523AY





US8 CASE 846AN



N5, WZ32 = Specific Device Code

KK = 2-Digit Lot Run Traceability Code
XY = 2-Digit Date Code Format
Z = Assembly Plant Code
A = Assembly Location
L = Wafer Lot Number
YW = Assembly Start Week

ORDERING INFORMATION

See detailed ordering, marking and shipping information in the package dimensions section on page 6 of this data sheet.

NOTE: Some of the devices on this data sheet have been **DISCONTINUED**. Please refer to the table on page 6.

Connection Diagrams

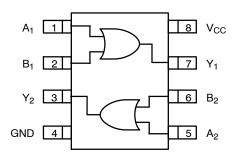


Figure 2. Connection Diagram (Top View)

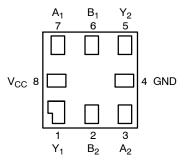
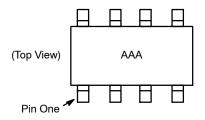


Figure 4. Pad Assignments for MicroPak (Top Thru View)



AAA represents Product Code Top Mark – see ordering code NOTE: Orientation of Top Mark determines Pin One location.

Read the top product code mark left to right, Pin One is the lower left pin (see diagram).

Figure 3. Pin One Orientation Diagram

PIN DESCRIPTIONS

Pin Names	Description
A _n , B _n	Inputs
Y _n	Output

FUNCTION TABLE (Y = A + B)

Inp	Output	
Α	В	Υ
L	L	L
L	Н	Н
Н	L	Н
Н	Н	Н

H = HIGH Logic Level L = LOW Logic Level

ABSOLUTE MAXIMUM RATINGS

Symbol	Para	Parameter		Max	Unit
V _{CC}	Supply Voltage		-0.5	6.5	V
V _{IN}	DC Input Voltage		-0.5	6.5	V
V _{OUT}	DC Output Voltage		-0.5	6.5	V
I _{IK}	DC Input Diode Current	V _{IN} < 0 V	-	-50	mA
l _{ok}	DC Output Diode Current	V _{OUT} < 0 V	-	-50	mA
I _{OUT}	DC Output Current	DC Output Current		±50	mA
I _{CC} / I _{GND}	DC V _{CC} / GND Current		-	±100	mA
T _{STG}	Storage Temperature		-65	+150	°C
TJ	Junction Temperature under Bia	as	-	150	°C

T _L	Junction Lead Temperature (Solde	ring, 10 Seconds)	-	260	°C
P _D	Power Dissipation in Still Air	Power Dissipation in Still Air US8		500	mW
		MicroPak-8	-	539	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

RECOMMENDED OPERATING CONDITIONS

Symbol		Parameter	Min	Max	Unit
V _{CC}	Supply Voltage Operating		1.65	5.5	V
	Supply Voltage Data Rete	ntion	1.5	5.5	
V _{IN}	Input Voltage		0	5.5	V
V _{OUT}	Output Voltage		0	V _{CC}	V
T _A	Operating Temperature		-40	+85	°C
t _r , t _f	Input Rise and Fall Time	V _{CC} = 1.80 V ±0.15 V, 2.5 V ±0.2 V	0	20	ns/V
		V _{CC} = 3.3 V ±0.3 V	0	10	
	V _{CC} = 5.0 V ±0.5 V		0	5	
θ_{JA}	Thermal Resistance	US8	-	250	°C/W
		MicroPak-8	-	232	

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

1. Unused inputs must be held HIGH or LOW. They may not float.

DC ELECTICAL CHARACTERISTICS

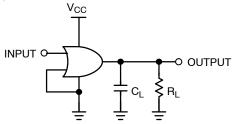
Symbo					٦	Γ _A = +25°(T _A = -40	to +85°C	
l	Parameter	Co	nditions	V _{CC} (V)	Min	Тур	Max	Min	Max	Unit
V _{IH}	HIGH Level Input Voltage			1.65 to 1.95	0.65 V _{CC}	-	-	0.65 V _{CC}	_	V
				2.3 to 5.5	0.7 V _{CC}	-	-	0.7 V _{CC}	_	
V _{IL}	LOW Level Input			1.65 to 1.95	-	-	0.35 V _{CC}	_	0.35 V _{CC}	V
	Voltage			2.3 to 5.5	-	-	0.3 V _{CC}	_	0.3 V _{CC}	
V _{OH}	HIGH Level Output	$V_{IN} = V_{IH}$	$I_{OH} = -100 \mu A$	1.65	1.55	1.65	-	1.55	_	٧
	Voltage	or V _{IL} ,		2.3	2.2	2.3	-	2.2	_	
				3.0	2.9	3.0	_	2.9	_	
				4.5	4.4	4.5	-	4.4	_	
			$I_{OH} = -4 \text{ mA}$	1.65	1.29	1.52	-	1.29	_	1
			$I_{OH} = -8 \text{ mA}$	2.3	1.9	2.15	-	1.9	_	1
			I _{OH} = -16 mA	3.0	2.4	2.80	-	2.4	_	
		I _{OH} = -24 mA	I _{OH} = -24 mA	3.0	2.3	2.68	_	2.3	_	
		I _{OH} = -32 mA	4.5	3.8	4.20	_	3.8	_	İ	
V _{OL}	LOW Level Output V _{IN} = V _{IH}		I _{OL} = 100 μA	1.65	-	0.0	0.1	_	0.1	٧
	Voltage	or V _{IL} ,		2.3	-	0.0	0.1	_	0.1	
				3.0	-	0.0	0.1	_	0.1	
				4.5	-	0.0	0.1	-	0.1	
			I _{OL} = 4 mA	1.65	-	0.08	0.24	_	0.24	
			I _{OL} = 8 mA	2.3	-	0.10	0.3	_	0.3	1
			I _{OL} = 16 mA	3.0	-	0.15	0.4	_	0.4	1
			I _{OL} = 24 mA	3.0	-	0.22	0.55	-	0.55	
		I _{OL} = 32 mA	I _{OL} = 32 mA	4.5	-	0.22	0.55	-	0.55	
I _{IN}	Input Leakage Current	V _{IN} = 5.5	V _{IN} = 5.5 V, GND		-	-	±0.1	-	±1	μΑ
l _{OFF}	Power Off Leakage Current	V _{IN} or V _{OU}	_T = 5.5 V	0.0	-	-	1	-	10	μА
I _{CC}	Quiescent Supply Current	V _{IN} = 5.5 V	, GND	1.65 to 5.5	-	-	1	-	10	μΑ

AC ELECTRICAL CHARACTERISTICS

Symbo					T _A = +25°C		T _A = -40	to +85°C	
I	Parameter	Conditions	V _{CC} (V)	Min	Тур	Max	Min	Max	Unit
t _{PLH} , t _{PHL}	Propagation Delay	C _L = 15 pF,	1.8 ±0.15	-	5.8	10.5	_	11	ns
	(Figure 5, 7)	$R_L = 1 M\Omega$	2.5 ±0.2	-	3.5	5.8	-	6.2	
			3.3 ±0.3	-	2.6	3.9	_	4.3	
			5.0 ±0.5	-	1.8	3.1	-	3.3	
		C _L = 50 pF,	3.3 ±0.3	-	3.2	4.8	_	5.2	
		$R_L = 500 \Omega$	5.0 ±0.5	-	2.4	3.7	-	4.0	
C _{IN}	Input Capacitance		0	-	2.5	-	_	_	pF
C _{PD} Power Dissipation Capacitanc	(Note 2)	3.3	-	14	_	-	-	pF	
	(Figure 6)		5.0	-	18	_	-	-	

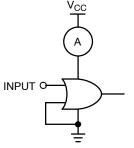
^{2.} C_{PD} is defined as the value of the internal equivalent capacitance which is derived from dynamic operating current consumption (I_{CCD}) at no output loading and operating at 50% duty cycle. (see Figure 6) C_{PD} is related to I_{CCD} dynamic operating current by the expression: I_{CCD} = (C_{PD}) (V_{CC}) (f_{IN}) + (I_{CC}static).

AC Loading and Waveforms



 C_L includes load and stray capacitance Input PRR = 1.0 MHz, $t_W = 500 \ \text{ns}$

Figure 5. AC Test Circuit



 $\begin{aligned} & \text{Input} = \text{AC Waveforms; } t_r = t_f = 1.8 \text{ ns;} \\ & \text{PRR} = 10 \text{ MHz; } \text{Duty Cycle} = 50\%. \end{aligned}$

Figure 6. I_{CCD} Test Circuit

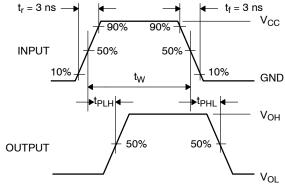


Figure 7. AC Waveforms

ORDERING INFORMATION

Order Number	Top Mark	Package	Shipping [†]
NC7WZ32K8X	WZ32	8-Lead US8, JEDEC MO-187, Variation CA 3.1 mm Wide	3000 / Tape & Reel
NC7WZ32L8X	N5	8-Lead MicroPak, 1.6 mm Wide (Pb-Free)	5000 / Tape & Reel

DISCONTINUED (Note 4)

NC7WZ32K8X-L22236	WZ32	8-Lead US8, JEDEC MO-187, Variation CA 3.1 mm Wide	3000 / Tape & Reel
NC7WZ32L8X-L22185	N5	8-Lead MicroPak, 1.6 mm Wide (Pb-Free)	5000 / Tape & Reel

For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging

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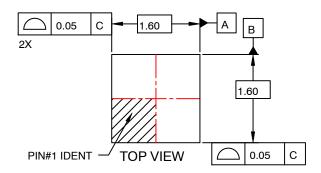


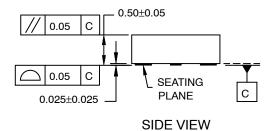
Specifications Brochure, BRD8011/D.
 Pb-Free package per JEDEC J-STD-020B.
 DISCONTINUED: These devices are not available. Please contact your onsemi representative for information. The most current information on these devices may be available on www.onsemi.com.

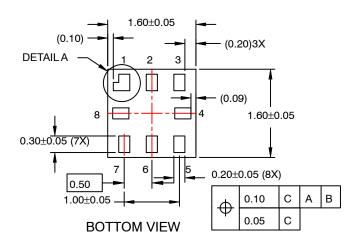


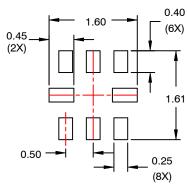
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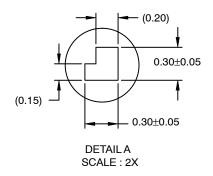




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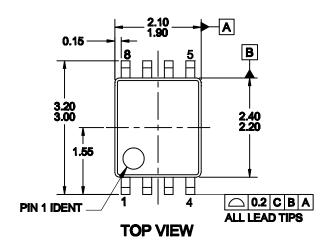
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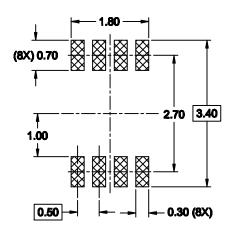
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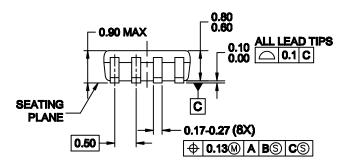
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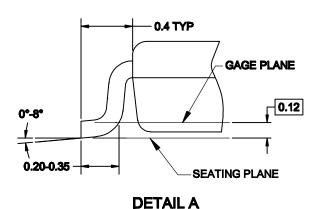
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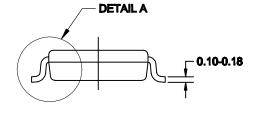


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SIDE VIEW





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